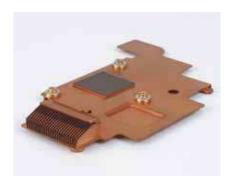
Hi-Flow® 225UT

Un-Reinforced, Pressure Sensitive Phase Change Thermal Interface Material

Features and Benefits

- Thermal impedance: 0.08°C-in²/W (@25 psi)
- 55°C phase change composite with inherent tack characteristics
- High-visibility protective tabs
- Pressure sensitive phase change thermal interface material



Hi-Flow 225UT is designed as a pressure sensitive thermal interface material for use between a high performance processor and a heat sink Hi-Flow 225UT is a thermally conductive 55°C phase change composite with inherent tack. The material is supplied on a polyester carrier liner and is available with high-visibility protective tabs.

Above its phase change temperature, Hi-Row 225UT wets-out the thermal interface surfaces and flows to produce the lowest thermal impedance. The material requires pressure of the assembly to cause flow. Hi-Row 225UT coatings will resist dripping.

Application Methods:

Hand-apply Hi-Row 225UT to a room-temperature heat sink The Hi-Row 225UT pad exhibits inherent tack and can be hand-applied similar to an adhesive pad. The tab liner can remain on the heat sink and pad throughout shipping and handling until is it is ready for final assembly.

TYPICAL PROPERTIES OF HI-FLOW 225UT						
PROPERTY	IMPERIALVALUE		METRIC VALUE		TEST METHOD	
Color	Black		Black		Visual	
Reinforcement Carrier	None		None		_	
Thickness (inch) / (mm)	0.003		0.077		ASTM D374	
Continuous Use Temp (℉) / (℃)	248		120		_	
Phase Change Temp (℉) / (℃)	131		55		ASTM D3418	
ELECTRICAL						
Flame Rating	V-O		V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W/m-K) (1)	0.7		0.7		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Pressure (psi)		10	25	50	100	200
TO-220 Thermal Performance (℃/W)		0.60	0.53	0.46	0.40	0.35
Thermal Impedance (℃-in²/W) (2)		0.09	80.0	0.07	0.06	0.05

1) This is the measured thermal conductivity of the Hi-Row coating it represents one conducting layer in a three-layer laminate. The Hi-Row coatings are phase change compounds These layers will respond to heat and pressure included stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if additional specifications are required.
2) The ASTM D5470 test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only Actual application performance is directly related to the surface roughness flatness and pressure applied.

Typical Applications Include:

- · Computer and peripherals
- High performance computer processors
- · Graphic cards
- · Power modules

Configurations Available:

• Roll form with tabs kiss-cut parts - no holes

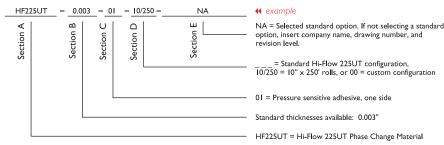
Hi-Row 225UT is limited to a square or rectangular part design. Dimensional tolerance is +/- 0.020 inch (0.5mm).

Roll Form, Kiss-Cut Parts Clear Polyester Carrier Liner

Clear/Colored

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

Hi- Flow®: U.S. Patent 6,197,859 and others



www.bergquistcompany.com